## MSKSEMI















**ESD** 

TVS

TSS

MOV

**GDT** 

**PLED** 

# Brodnet data speet

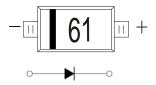
www.msksemi.com





SOD-523

#### **MARKING:61**



#### **BAS516 FAST SWITCHING DIODE**

#### **FEATURES**

- Small Package
- Low Reverse Current
- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion

#### MAXIMUM RATINGS ( T<sub>a</sub>=25℃ unless otherwise noted )

Symbol	Parameter	Value	Unit	
$V_{RM}$	Non-Repetitive Peak Reverse Voltage	100	V	
$V_{RRM}$	Peak Repetitive Reverse Voltage 75		V	
$V_{RWM}$	Working Peak Reverse Voltage	13	V	
V <sub>R(RMS)</sub>	RMS Reverse Voltage	53	V	
lo	Average Rectified Output Current	250	mA	
I <sub>FSM</sub>	Non-repetitive Peak Forward Surge Current @t=8.3ms	2.0	Α	
P <sub>D</sub>	Power Dissipation	150	mW	
R <sub>OJA</sub>	Thermal Resistance from Junction to Ambient	833	°C/W	
T <sub>j</sub>	Junction Temperature	150	℃	
T <sub>stg</sub>	Storage Temperature	-55~+150	$^{\circ}$	

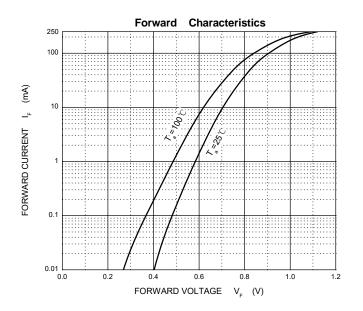
#### **ELECTRICAL CHARACTERISTICS(Ta=25℃ unless otherwise specified)**

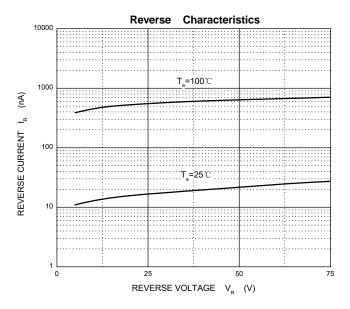
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Reverse voltage	$V_{(BR)}$	I <sub>R</sub> =100μA	75			V
Reverse current	I <sub>R</sub>	V <sub>R</sub> =25V			30	nA
		V <sub>R</sub> =75V			1	μА
Forward voltage	V <sub>F</sub>	I <sub>F</sub> =1mA			0.715	V
		I <sub>F</sub> =10mA			0.855	V
		I <sub>F</sub> =50mA			1	V
		I <sub>F</sub> =150mA			1.25	V
Total capacitance	C <sub>tot</sub>	V <sub>R</sub> =0V,f=1MHz			1	pF
Reverse recovery time	t <sub>rr</sub>	$I_{F}=I_{R}=10$ mA, $I_{rr}=0.1*I_{R}$ , $R_{L}=100$ $\Omega$			4	ns

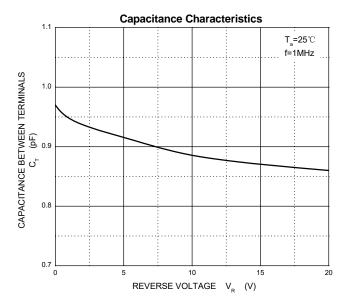


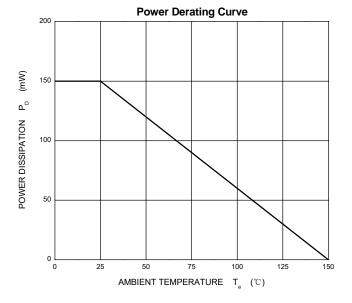
## **Typical Characteristics**



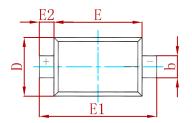


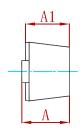


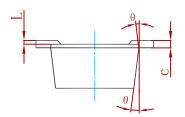




## **PACKAGE MECHANICAL DATA**

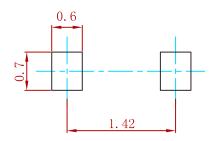






Symbol	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min	Max	Min	Max
Α	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
С	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
Е	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
Ш	0.010	0.070	0.001	0.003
θ	7° REF		7° F	REF

## **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
BAS516	SOD-523	3000



### Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specificationsof any andall MSKSEMI Semiconductor products described orcontained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with someprobability. It is possiblethat these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits anderror prevention circuitsfor safedesign, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from theauthorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringementsof intellectual property rights or other rightsof third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. Whendesigning equipment, referto the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.

## 单击下面可查看定价,库存,交付和生命周期等信息

>>MSKSEMI (美森科)